



# SLOVENSKI STANDARD

## SIST EN 62047-21:2014

01-november-2014

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**Polprevodniški elementi - Mikroelektromehanski elementi - 21. del: Preskusne metode za Poissonovo razmerje tankoplastnih materialov MEMS (IEC 62047-21:2014)**

Semiconductor devices - Micro-electromechanical devices - Part 21: Test method for Poisson's ratio of thin film MEMS materials

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Dispositifs à semiconducteurs - Dispositifs microélectromécaniques - Partie 21: Méthode d'essai relative au coefficient de Poisson des matériaux MEMS en couche mince

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**Ta slovenski standard je istoveten z: EN 62047-21:2014**

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**ICS:**

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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EUROPEAN STANDARD

**EN 62047-21**

NORME EUROPÉENNE

EUROPÄISCHE NORM

September 2014

ICS 31.080.99

English Version

Semiconductor devices - Micro-electromechanical devices -  
Part 21: Test method for Poisson's ratio of thin film MEMS  
materials  
(IEC 62047-21:2014)

Dispositifs à semiconducteurs - Dispositifs  
microélectromécaniques -  
Partie 21: Méthode d'essai relative au coefficient de  
Poisson des matériaux MEMS en couche mince  
(CEI 62047-21:2014)

Halbleiterbauelemente - Bauelemente der  
Mikrosystemtechnik -  
Teil 21: Prüfverfahren zur Querkontraktionszahl von  
Dünnschichtwerkstoffen der Mikrosystemtechnik  
(IEC 62047-21:2014)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

## Foreword

The text of document 47F/185/FDIS, future edition 1 of IEC 62047-21, prepared by SC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-21:2014.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2015-04-24
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2017-07-24

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-8	2011	Semiconductor devices - Micro-electromechanical devices - Part 8: Strip bending test method for tensile property measurement of thin films	EN 62047-8	2011
ASTM E132-04	2010	Standard test method for Poisson's ratio at room temperature	-	-

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IEC 62047-21

Edition 1.0 2014-06

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Semiconductor devices – Micro-electromechanical devices –  
Part 21: Test method for Poisson's ratio of thin film MEMS materials**

**Dispositifs à semiconducteurs – Dispositifs microélectromécaniques –  
Partie 21: Méthode d'essai relative au coefficient de Poisson des matériaux  
MEMS en couche mince**

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COMMISSION

COMMISSION  
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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –  
MICRO-ELECTROMECHANICAL DEVICES –**

**Part 21: Test method for Poisson's ratio  
of thin film MEMS materials**

## FOREWORD

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International Standard IEC 62047-21 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/185/FDIS	47F/189/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.